

Remarks/Arguments

Applicant thanks Examiner Novacek for her careful examination of this application and clear explanation of the claims rejections, and for allowing claims 16-18. In response, applicant amends the preambles of claims 1, 9, 16; and claims 7, 8, 14, 15, 19, and 20 to overcome the 112 rejections. Applicant further amends claims 1 and 9 to include all the elements that Examiner Novecek noted in allowing claim 16-18, namely, a pre-warped configuration for the cavity based on an anticipated warpage of the mold compound when removed from the cavity and further a predefined configuration of the mold compound after curing.

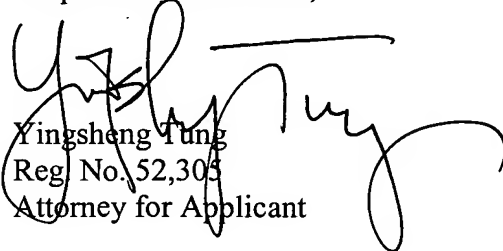
Alternatively, applicant submits that since the Cochnour does not disclose a first mold press die and a second mold press die as required in claims 1 and 9, and since the Cochnour does not disclose removing the encapsulation from the cavity and curing the mold compound as further required in claim 1, it does not anticipate claims 1 and 9.

Applicant respectfully submits that, with the added limitations, claims 1 and 9 distinguish over the Cochnour patent and stand patentable. Because claims 2-8 depend from claim 1 and claims 10-15 depend from claim 9, they also stand patentable.

In summary, applicant respectfully submits that this application is now in allowable form and all pending claims distinguish over the cited references. Applicant respectfully requests further examination of this application and timely allowance of all pending claims.

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Respectfully submitted,


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